



## Material Content Data Sheet



<b>Sales Product Name</b>		TDA21220		<b>Issued</b>		22. May 2015		
<b>MA#</b>		MA000873774						
<b>Package</b>		PG-IQFN-40-1		<b>Weight*</b>		99.90 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.536	1.54	1.54	15376	15376
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		128	
	non noble metal	zinc	7440-66-6	0.051	0.05		511	
	non noble metal	iron	7439-89-6	1.020	1.02		10213	
	non noble metal	copper	7440-50-8	41.428	41.47	42.55	414709	425561
wire	noble metal	gold	7440-57-5	0.308	0.31	0.31	3080	3080
encapsulation	organic material	carbon black	1333-86-4	0.086	0.09		858	
	plastics	epoxy resin	-	4.415	4.42		44196	
	inorganic material	silicondioxide	60676-86-0	38.363	38.40	42.91	384035	429089
leadfinish	non noble metal	tin	7440-31-5	1.587	1.59	1.59	15887	15887
plating	noble metal	silver	7440-22-4	1.920	1.92	1.92	19223	19223
glue	plastics	epoxy resin	-	0.123	0.12		1235	
	noble metal	silver	7440-22-4	0.370	0.37	0.49	3705	4940
solder	noble metal	silver	7440-22-4	0.027	0.03		266	
	non noble metal	tin	7440-31-5	0.021	0.02		213	
	non noble metal	lead	7439-92-1	1.016	1.02	1.07	10166	10645
CLIP plating	noble metal	silver	7440-22-4	0.787	0.79	0.79	7877	7877
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		20	
	non noble metal	zinc	7440-66-6	0.008	0.01		82	
	non noble metal	iron	7439-89-6	0.164	0.16		1640	
	non noble metal	copper	7440-50-8	6.651	6.66	6.83	66580	68322
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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